



T-77-05-07

SL6440A & C

HIGH LEVEL MIXER

The SL6440 is a double balanced mixer intended for use in radio systems up to 150MHz. A special feature of the circuit allows external selection of the DC operating conditions by means of a resistor connected between pin 11 (bias) and Vcc. When biased for a supply current of 50mA the SL6440 offers a 3rd order intermodulation intercept point of typically +30dBm, a value previously unobtainable with integrated circuits. This makes the device suitable for many applications where diode ring mixers had previously been used and offers the advantages of a voltage gain, low local oscillator drive requirement and superior isolation.

The SL6440C is in a 16-lead DIL plastic package (DP), and is specified for operation from -30°C to +85°C; the SL6440A is in a ceramic DIL package (DG) and has military temperature range specification of -55°C to +125°C.

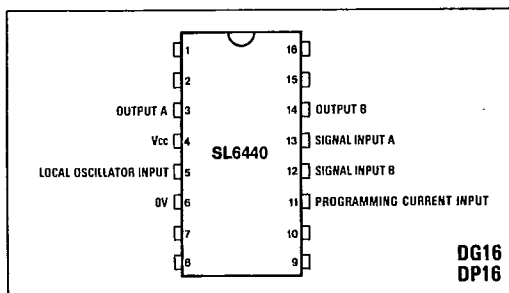


Fig.1 Pin connections - top view

FEATURES

- +30dBm Input Intercept Point
- +15dBm Compression Point (1dB)
- Programmable Performance
- Full Military Temperature Range (SL6440A)

APPLICATIONS

- Mixers in Radio Transceivers
- Phase Comparators
- Modulators

ELECTRICAL CHARACTERISTICS

Test conditions (unless otherwise stated):

Vcc1 = 12V; Vcc2 = 10V; I_p = 25mA; T_{amb} = -55°C to +125°C (SL6440A), -30°C to +85°C (SL6440C)
 Local oscillator input level = 0dBm; Test circuit Fig.2.

ABSOLUTE MAXIMUM RATINGS

Supply voltage and output pins	15V
Maximum power dissipation (Derate above 25°C: 8mW/°C)	1200mW
Storage temperature range	-65°C to +150°C
Programming current into pin 11	50mA

THERMAL CHARACTERISTICS

Thermal resistance: θ _{JA}	125°C/W
θ _{JC}	40°C/W
Time constant: Junction-Ambient	1.9 mins
Maximum chip temperature	150°C

Characteristic	Value			Units	Conditions
	Min.	Typ.	Max.		
Signal frequency 3dB point	100	150		MHz	} Two 0dBm input } Signals Vcc1 = 15V Vcc2 = 12V Vcc1 = 12V Vcc2 = 10V Fig.8 test circuit 50Ω load Fig.2 Test circuit Fig.8 See applications information I _p = 0 I _p = 35mA
Oscillator frequency 3dB point	100	150		MHz	
3rd order input intercept point		+30		dBm	
Third order intermodulation distortion		-60		dB	
Second order intermodulation distortion		-75		dB	
1dB compression point		15		dBm	
Noise figure		11		dB	
Conversion gain		-1		dB	
Carrier leak to signal input	-40			dB	
Level of carrier at IF output		-25		dBm	
Supply current		7		mA	
Supply current (total from Vcc1 & Vcc2)		60		mA	
Local oscillator input	100	250	500	mV rms	
Local oscillator input impedance		1.5		kΩ	
Signal input impedance		500		Ω	
		1000		Ω	

NOTE Supply current in Pin 3 is equal to that in Pin 14 and is equal to I_p. See over. V_{pin11} = 3 V_{be} = 2.1V.

CIRCUIT DESCRIPTION

The SL6440 is a high level mixer designed to have a linear RF performance. The linearity can be programmed using the I_p pin (11).

The output pins are open collector outputs so that the conversion gain and output loads can be chosen for the specific application.

Since the outputs are open collectors they should be returned to a supply V_{cc1} through a load.

The choice of V_{cc1} is important since it must be ensured that the voltage on pins 3 and 14 is not low enough to saturate the output transistors and so limit the signal swing unnecessarily. If the voltage on pins 3 and 14 is always greater than V_{cc2} the outputs will not saturate. The output frequency response will reduce as the output transistors near saturation.

Minimum $V_{cc1} = (I_p \times RL) + V_s + V_{cc2}$
 where I_p = programmed current
 RL = DC load resistance
 V_s = max signal swing at output
 if the signal swing is not known:
 minimum $V_{cc1} = 2 (I_p \times RL) + V_{cc2}$

In this case the signal will be limiting at the input before the output saturates.

The device has a separate supply (V_{cc2}) for the oscillator buffer (pin 4).

The current (I_p) programmed into pin 11 can be supplied via a resistor from V_{cc1} or from a current source.

The conversion gain is equal to

$$GdB = 20 \text{ Log } \frac{RL I_p}{56.61 I_p + 0.0785} \text{ for single-ended output}$$

$$GdB = 20 \text{ Log } \frac{2 RL I_p}{56.61 I_p + 0.0785} \text{ for differential output}$$

Device dissipation is calculated using the formula

mW diss = $2 I_p V_o + V_p I_p + V_{cc2} \text{ Diss}$
 where V_o = voltage on pin 3 or pin 14
 V_p = voltage on pin 11
 I_p = programming current (mA)
 $V_{cc2} \text{ Diss}$ = dissipation obtained from graph (Fig.6)

As an example Fig. 7 shows typical dissipations assuming V_{cc1} and V_o are equal. This may not be the case in practice and the device dissipation will have to be calculated for any particular application.

Fig.5 shows the intermodulation performance against I_p . The curves are independent of V_{cc1} and V_{cc2} but if V_{cc1} becomes too low the output signal swing cannot be accommodated, and if V_{cc2} becomes too low the circuit will not provide enough drive to sink the programmed current. Examples are shown of performance at various supply voltages.

The current in pin 14 is equal to the current in pin 3 which is equal to the current in pin 11.

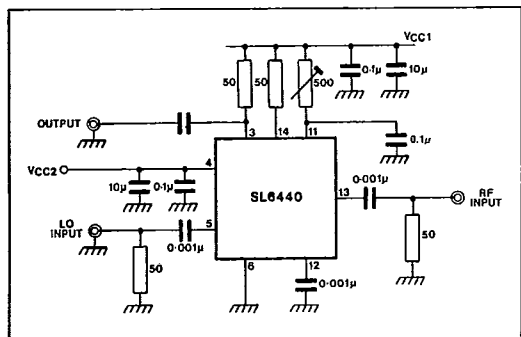


Fig.2 Typical application and test circuit

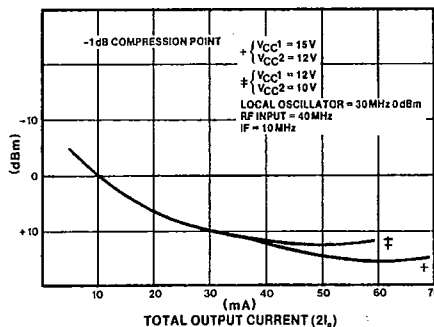


Fig.3 Compression point v. total output current

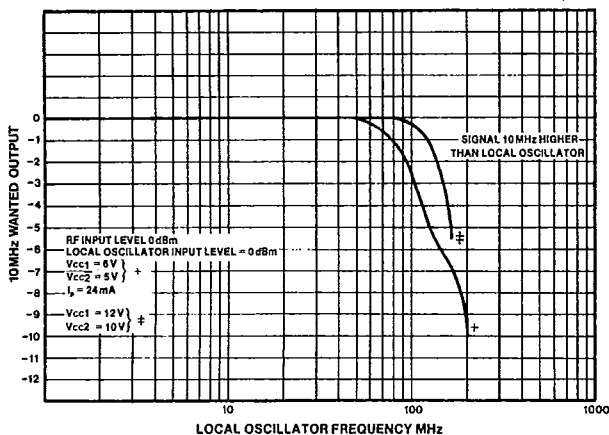


Fig.4 Frequency response at constant output IF

PLESSEY SEMICONDUCTORS

T-77-05-07

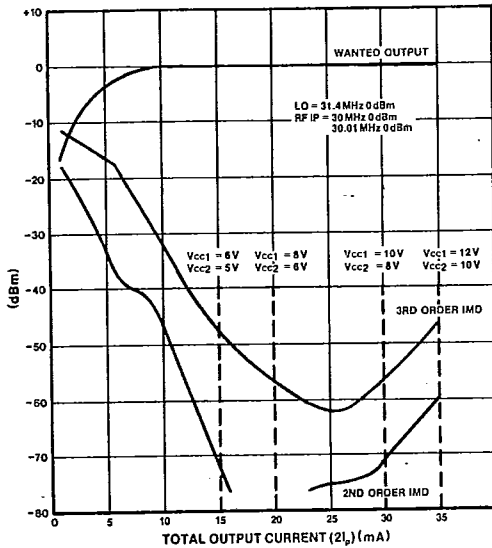


Fig.5 Intermodulation v. programming current

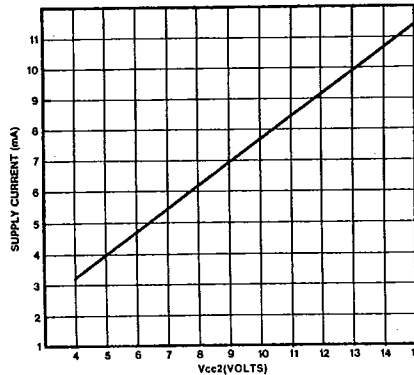


Fig.6 Supply current v. Vcc2 (I_p = 0)

APPLICATIONS

The SL6440 can be used with differential or single-ended inputs and outputs. A balanced input will give better carrier leak. The high input impedance allows step-up transformers to be used if desired, whilst high output impedance allows a choice of output impedance and conversion gain.

Fig. 2 shows the simplest application circuit. The input and output are single-ended and I_p is supplied from Vcc1 via a resistor. Increasing R_L will increase the conversion gain, care being taken to choose a suitable value for Vcc1.

Fig. 8 shows an application with balanced input, for improved carrier leak, and balanced output for increased conversion gain. A lower Vcc1 giving lower device dissipation can be used with this arrangement.

DESIGN PROCEDURE

1. Decide on input configuration using local oscillator data. If using transformer on input, decide on ratio from noise considerations.
2. Decide on output configuration and value of conversion gain required.
3. Decide on value of I_p and Vcc2 using intermodulation and compression point graphs.
4. Using values of conversion gain, Vcc2, load and I_p already chosen, decide on value of Vcc1.
5. Calculate device dissipation and decide whether heatsink is required from maximum operating temperature considerations.

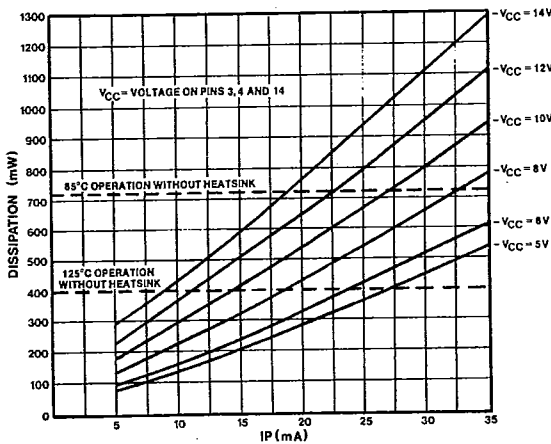


Fig.7 Device dissipation v. I_p

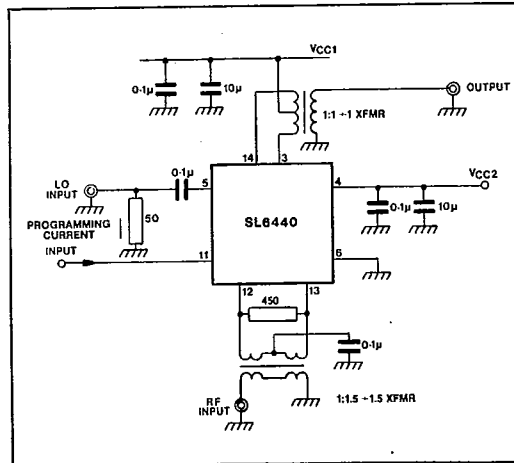


Fig.8 Typical application circuit for highest performance